



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: W1905-01	DATE: 13-Jun-2019	MEANS OF DISTINGUISHING CHANGED DEVICES:
Product Affected: Refer to attachment 2		☐ Product Mark ☐ Back Mark ☐ Date Code ☒ Other
Date Effective: 13-Sep-2019		Traceability to the Fab location is provided through the 2 digit sequential lot code on the date code line of the top mark.
Contact: IDT PCN DESK	Attachment: ☒ Yes ☐ No	
E-mail: pcndesk@idt.com	Samples: Please contact your local sales representative for sample request.	

DESCRIPTION AND PURPOSE OF CHANGE:

- | | |
|--|--|
| ☐ Die Technology | This notification is to advise our customers that IDT has qualified TSMC Fab 6 as an alternate Foundry for the products listed on this notice. |
| ☐ Wafer Fabrication Process | |
| ☐ Assembly Process | This is to provide additional manufacturing capacity for these products. |
| ☐ Equipment | There is no change to the product design or process technology as the existing qualified Foundry, TSMC Fab 8. |
| ☐ Material | |
| ☐ Testing | |
| ☒ Manufacturing Site | There is also no change to the package, backend manufacturing process or the the data sheet. |
| ☐ Data Sheet | |
| ☐ Other | Refer to page 2 for the qualification report. |

RELIABILITY/QUALIFICATION SUMMARY:

Based on wafer and component level qualification to date and characterization tests, there is no change to the performance or reliability of the product.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	☐ <i>Approval for shipments prior to effective date.</i>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____

Qualification Report

Device Family:	AW670T	Process Technology:	CM018HV, 1P4M
Package Type:	NDG48 (VFQFPN)	Fab Location:	TSMC Fab 6

Test Description	Standard	Test Conditions	Sample Size	Reject	Comments
Device Characterization	IDT's datasheet condition		80	0	Pass
ESD: Human Body Model	JESD22-A114 (JS-001) Classification – 1B	1 KV	3	0	Pass 1KV
ESD: Charged Device Model	JESD22-C101 Classification – C1	500 V	3	0	Pass 500V
Latch-Up	JESD78	+/-100mA I/O and 1.5x V _{cc} OV stress, Class II (85°C)	3	0	Pass
Early Life Failure Rate (ELFR)	JESD22-A108, JESD74	48 hrs. @ 125 °C, V _{cc} = 20V	834	0	Pass
High Temperature Operating Life (HTOL)	JESD22-A108, +125°C, V _{cc} -max	1,000 hrs. @ 125 °C, V _{cc} =20V	77	0	Pass
High Temperature Storage (HTS)	JESD22-A103	150°C, 1000 hrs	77	0	Pass

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ATTACHMENT 2 - PCN # : W1905-01

Affected Part Numbers

Part Number	Part Number	Part Number	Part Number
P9235A-0NDGI	P9235A-B0NDGI8	P9236A-B0NDGI	P9242-RBNDGI/B
P9235A-0NDGI8	P9235A-RBNDGI	P9236A-B0NDGI8	P9242-RBNDGI8
P9235A-16NDGI	P9235A-RBNDGI8	P9236A-B1NDGI	P9242-RBNDGI8/B
P9235A-16NDGI8	P9235A-RNDGI	P9236A-B1NDGI8	P9242-RNDGI
P9235A-18NDGI	P9235A-RNDGI8	P9242-R0NDGI	P9242-RNDGI8
P9235A-18NDGI8	P9236A-0NDGI	P9242-R0NDGI8	
P9235A-B0NDGI	P9236A-0NDGI8	P9242-RBNDGI	